



**THE DATASHEET OF
CIS10P700AC**



Chip Bead For EMI Suppression

CIS10P Series (1608/ EIA 0603)



APPLICATION

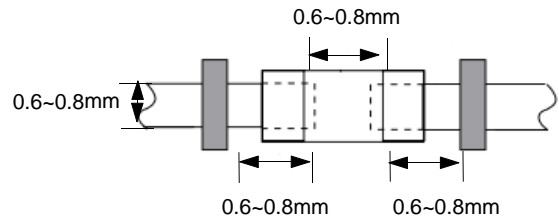
Noise Suppression in power line

FEATURES

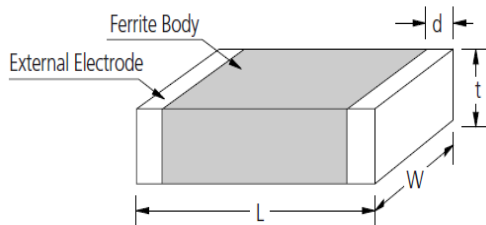
Smallest beads used in high current.

- CIS series is used for high current. (~ 6A)

RECOMMENDED LAND PATTERN



DIMENSION



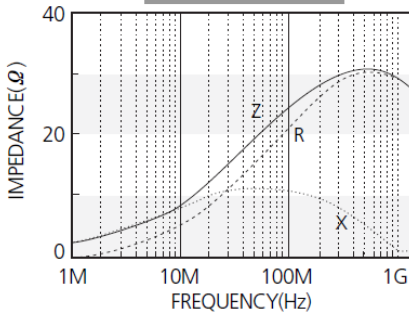
| Type | Dimension [mm] | | | |
|------|----------------|--------------|-----------------------|-------------|
| | L | W | t | d |
| 10 | 1.6 ±0.15 | 0.8 ±0.15 | 0.6±0.15, 0.8±0.15 | 0.3 ±0.2 |

DESCRIPTION

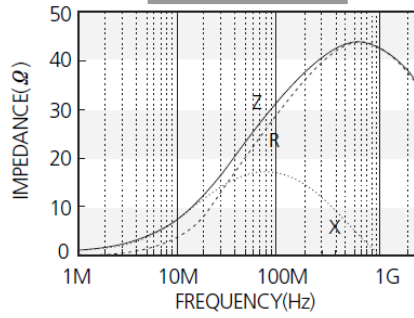
| Part No. | Thickness (mm) | Impedance (Ω)±25%@100MHz | DC Resistance (Ω) Max. | Rated Current (mA) Max. |
|-------------|----------------|-----------------------------------|---------------------------------|-------------------------|
| CIS10P260AC | 0.6±0.15 | 26 | 0.007 | 6000 |
| CIS10P300AC | 0.6±0.15 | 30 | 0.01 | 6000 |
| CIS10P700AC | 0.6±0.15 | 70 | 0.02 | 4000 |
| CIS10P101AC | 0.6±0.15 | 100 | 0.03 | 3000 |
| CIS10P121AC | 0.6±0.15 | 120 | 0.03 | 3000 |
| CIS10P181AC | 0.6±0.15 | 180 | 0.04 | 2500 |
| CIS10P221NC | 0.8±0.15 | 220 | 0.05 | 2500 |
| CIS10P301NC | 0.8±0.15 | 300 | 0.07 | 2000 |
| CIS10P331NC | 0.8±0.15 | 330 | 0.07 | 1700 |
| CIS10P391NC | 0.8±0.15 | 390 | 0.10 | 1200 |
| CIS10P471NC | 0.8±0.15 | 470 | 0.13 | 1500 |
| CIS10P601NC | 0.8±0.15 | 600 | 0.15 | 1300 |

CHARACTERISTIC DATA

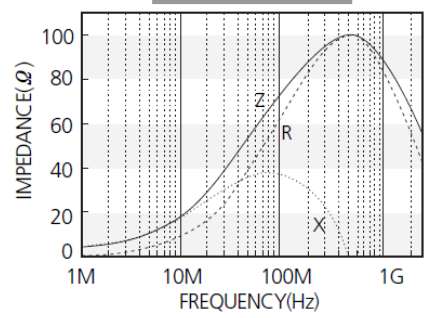
CIS10P260



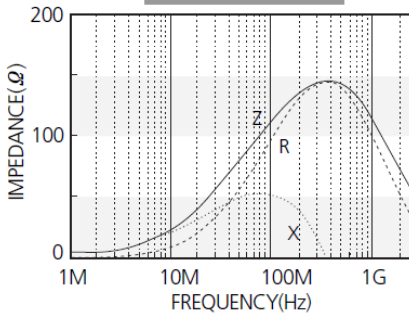
CIS10P300



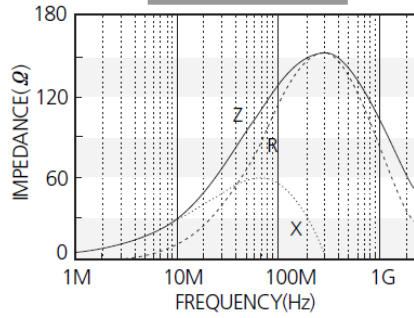
CIS10P700



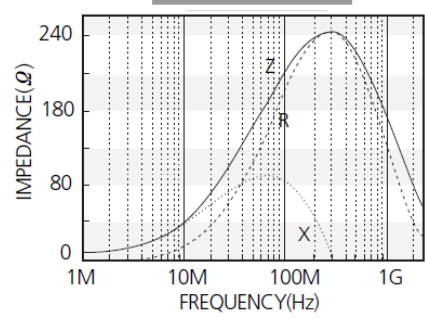
CIS10P101



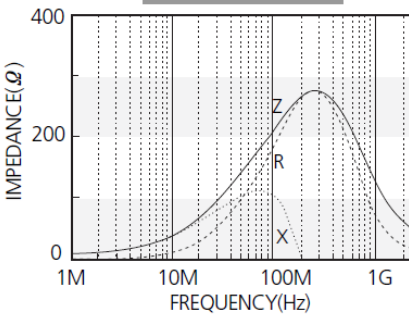
CIS10P121



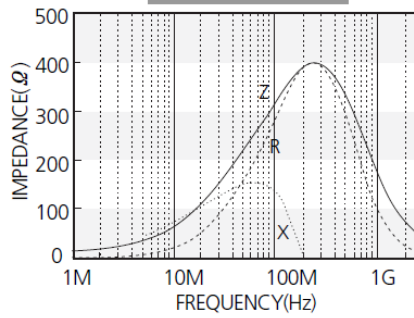
CIS10P181



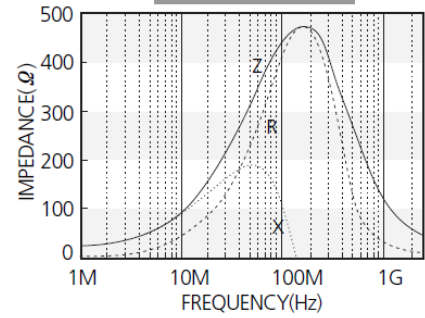
CIS10P221



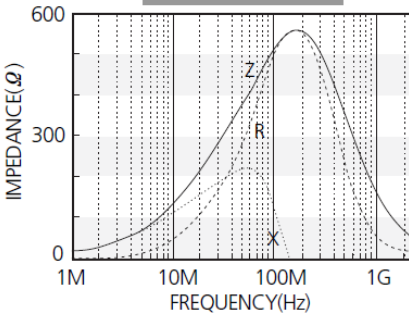
CIS10P331



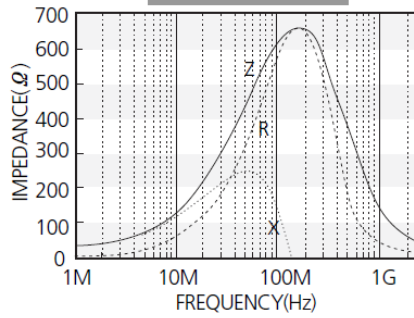
CIS10P391



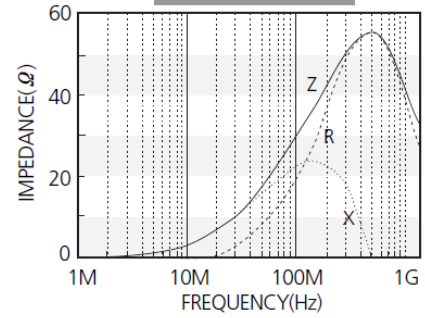
CIS10P471



CIS10P601



CIS10J300



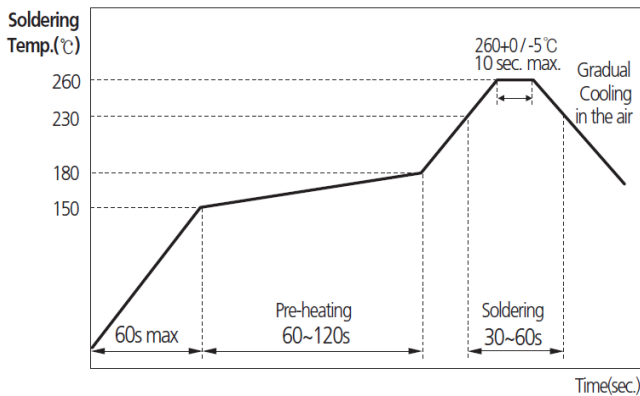
PRODUCT IDENTIFICATION

CI S 10 P 300 A C
(1) (2) (3) (4) (5) (6) (7)

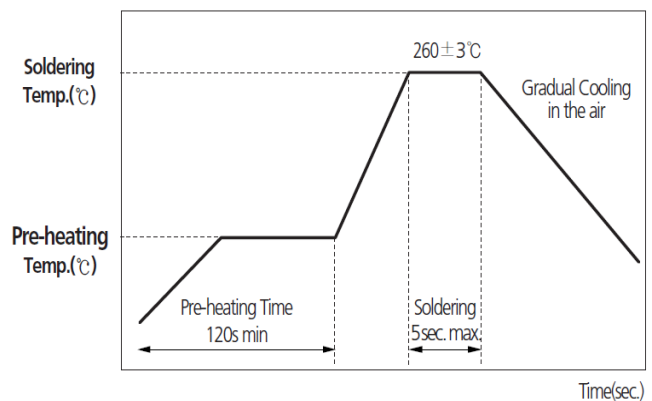
- (1) Chip Beads
- (2) Ultra high current (~6A)
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (300:30Ω, 121:120Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

| Packaging Style | Quantity(pcs/reel) |
|-------------------|--------------------|
| Card Board Taping | 4000 |

Looking for pricing, stock, or lifecycle information?

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- ⊖ [Samsung](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management